

## ADVANCED DIRECT MAGING by ALTIX

# DIX SA SUPRO







#### **DIRECT IMAGING LITHOGRAPHY**

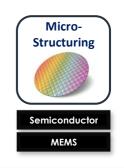
#### FOR THE MOST ADVANCED FINELINE APPLICATIONS











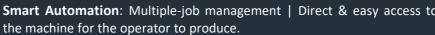


#### FOR ADVANCED FINELINE APPLICATIONS

### **ADIX SA** supra

<b>AUN SA</b> Supra		
Applications	IC Substrate   Advanced Packaging   HDI   Advanced Flex   Thin Film Supports Flip-Chip BGA, Flip-Chip CSP & Modules manufacturing applications Support FOPLP (Fan Out Panel Level packaging)   RDL (Redistribution layer)	
Material	Panel Substrate & Glass Carrier: Up to 600x600mm   23.6"x23.6" Wafer: Up to 300mm Thickness: Up to 4mm   0.157"	
Resolution Alignment	Line: 8μm   0.3mil – Pitch: 20μm   0.8 mil – SRO/Dam: 30μm   1.2 mils Image to Panel: ±7μm   ±0.3mil	
Throughput	46 sides/hour with 30mJ/cm2 resist for 600x600mm (23.6"x 23.6") [6 PH] Data preprocessing in hidden time + High UV Power with 4 LEDs per PH	300
Smart	SKATE: Offline machine set-up: Job preparation – Reduce operator mistakes.  Smart Automation: Multiple-job management   Direct & easy access to	

Smart Features



**Industry 4.0**: Auto-job preparation, system connectivity & remote access.

Unique Features



#### Die Positioning Compensation

DPC is a software designed to automatically adjust positioning and reroute tracks as needed for optimal die connection.



#### Partitioning & Multi-Panel Mode

Sub-area registration and printing: up to 16 areas. Scale & Align each subimage.

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